

Technical Specification (TM01LA-N)

History

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1. Product Introduction

The TM01LA-N are designed for the automotive industry. They support LTE, WCDMA and GSM air Interface standards. They also have Global Navigation satellite system (GNSS) capabilities including GPS and GLONASS.

The TM01LA-N are based on the Qualcomm MDM9215 wireless chipsets and support the following bands.

Table 1. Supported Band

Region		NA	TML1-E	TML1-C
Band	LTE	B2/B4/B5/B7/B17		
	WCDMA	B2/B4/B5		
	GSM	GSM850/PCS1900		
GNSS		O		
Voice		O		

1.1 Block Diagram

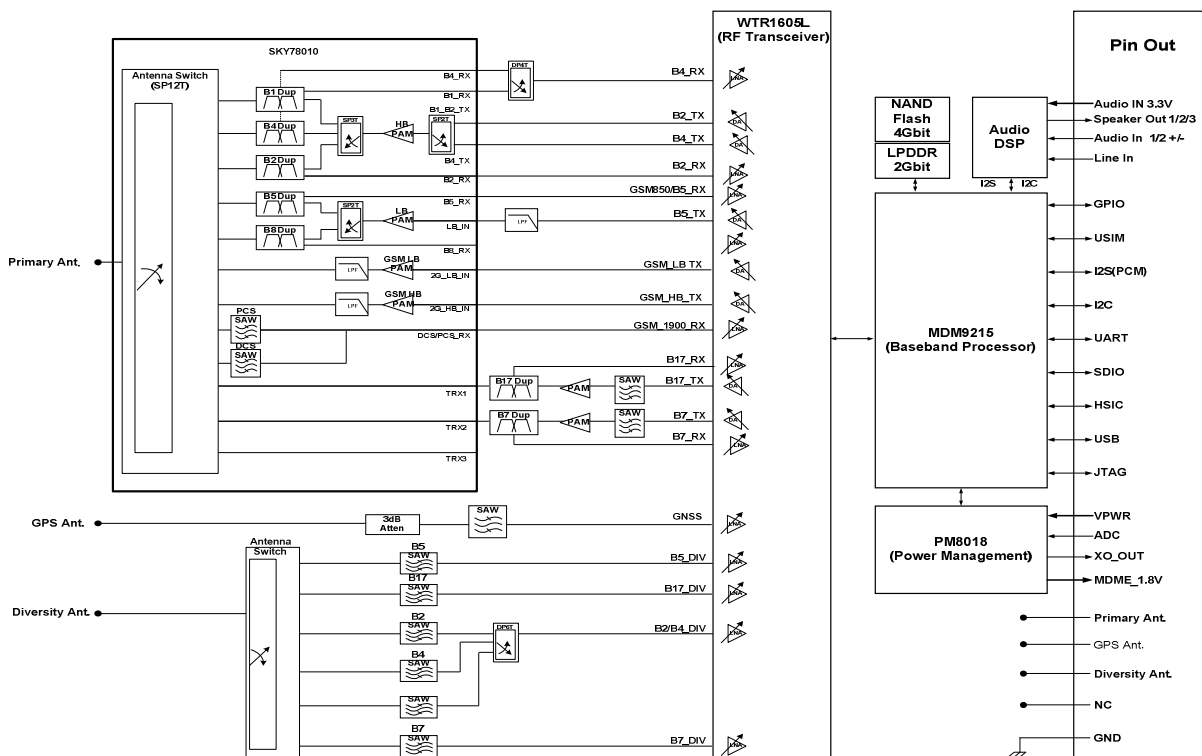


Figure 1.1. TM01LA-N Block diagram

1.2 Environmental Specifications

The environmental specification for operating and storage of the TM01LA-N are defined in the table below.

LGE guarantee the automotive operation by internal reliability verification

Table 2. Environmental Specifications

Parameter	Temperature Range
Operating Temperature	1) -40°C to 85°C
Storage Temperature	2) -40°C to +105°C
Humidity	95% or less

1) At 90°C operating, there is some deviation, but a module can meet 3GPP RF HW Spec

2) A module can accept over 105 °C storage temperature without packing

A module was guaranteed 34.2 MTTF in worst case at least

1.3 Electrical Specifications

This section provides details for some of the key electrical specifications of the TM01LA-N embedded modules.

1.3.1 Absolute Maximum Rating and ESD Ratings

This section defines the Absolute Maximum and Electrostatic Discharge (ESD) Ratings of the TM01LA-N embedded modules.

Warning: If these parameters are exceeded, even momentarily, damage may occur to the device.

Table 3. Absolute Maximum Ratings

Parameter		Min	Max	Units
+3.7V_VPWR	Power Supply Input	-	tbd	V
VIN	Voltage on any digital input or output pin	-	VREG_MDME+0.5	V
Maximum Voltage applied to antenna interface pins				
VANT	Primary Antenna		tbd	V
	Diversity Antenna		tbd	V
	GNSS Antenna		tbd	V
ESD Ratings				
ESD ¹	Primary, Diversity and GNSS antenna pads - Contact		tbd	kV
	All other signal pads - Contact		tbd	kV

1 The ESD Simulator configured with 330pF, 1000Ω.

Caution: The TM01LA-N embedded modules are sensitive to Electrostatic Discharge. ESD countermeasures and handling methods must be used when handling the TM01LA-N devices.

1.3.2 Current Consumption

Table 4. TM01LA-N Current Consumption (TBD)

Mode	Parameter	Typical	Max	Units
WCDMA	Band 2, Max TX Output Power			mA
	Band 4, Max TX Output Power			
	Band 5, Max TX Output Power			
LTE	Band2, Max TX Output /Full RB			mA
	Band4, Max TX Output /Full RB			
	Band5, Max TX Output /Full RB			
	Band7, Max TX Output /Full RB			
	Band17, Max TX Output /Full RB			
GSM	850/900MHz PCL5			mA
	1800/1900MHz PCL0			
WCDMA	Idle, Registered			mA
LTE	Idle, Registered			mA
GSM	Idle, Registered			mA
WCDMA	Sleep Mode, Average Current			mA
LTE	Sleep Mode, Average Current			mA
GSM	Sleep Mode, Average Current			mA

1.4 Mechanical Specifications

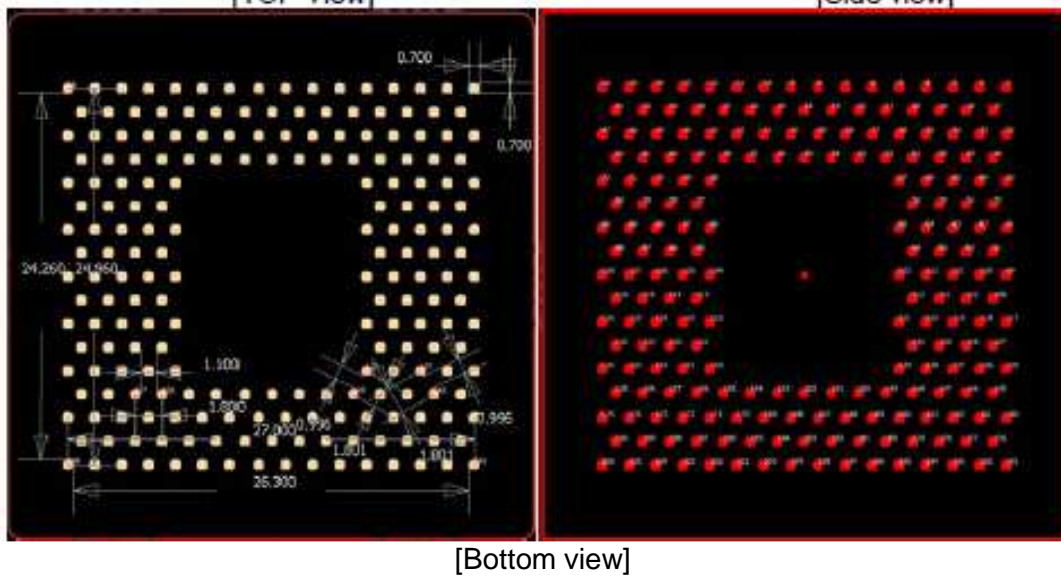
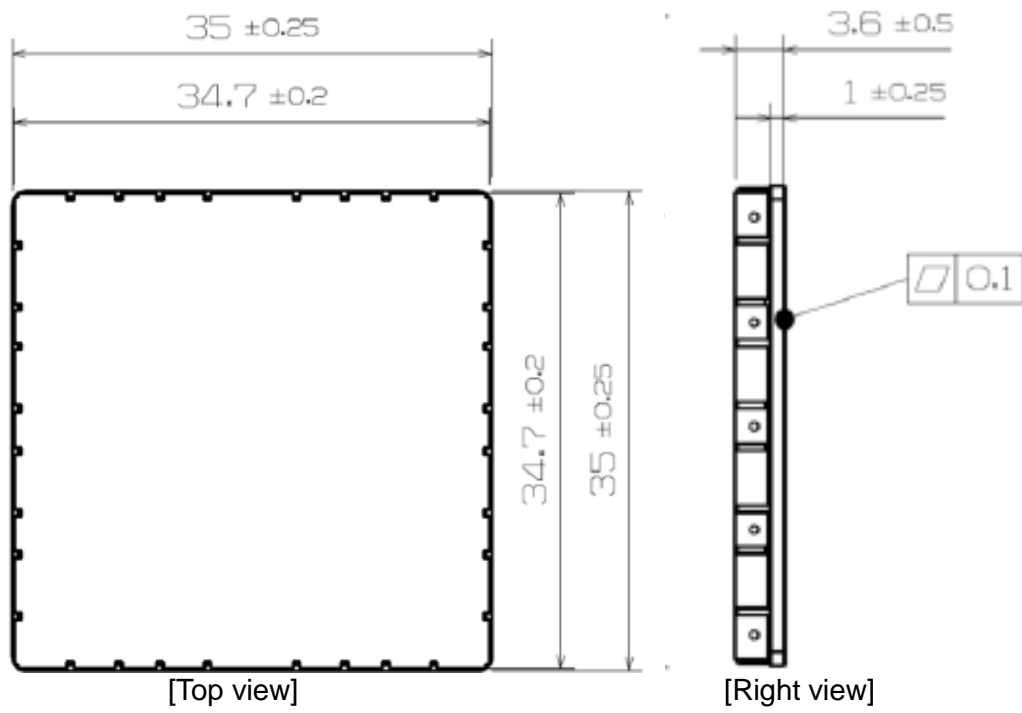
1.4.1 Physical Dimensions and Connection Interface

The TM01LA-N embedded modules are a Land Grid Array (LGA) form factor device. The device does not have a System or RF connectors. All electrical and mechanical connections are made via the 206 pad TM01LA-N on the underside of the PCB.

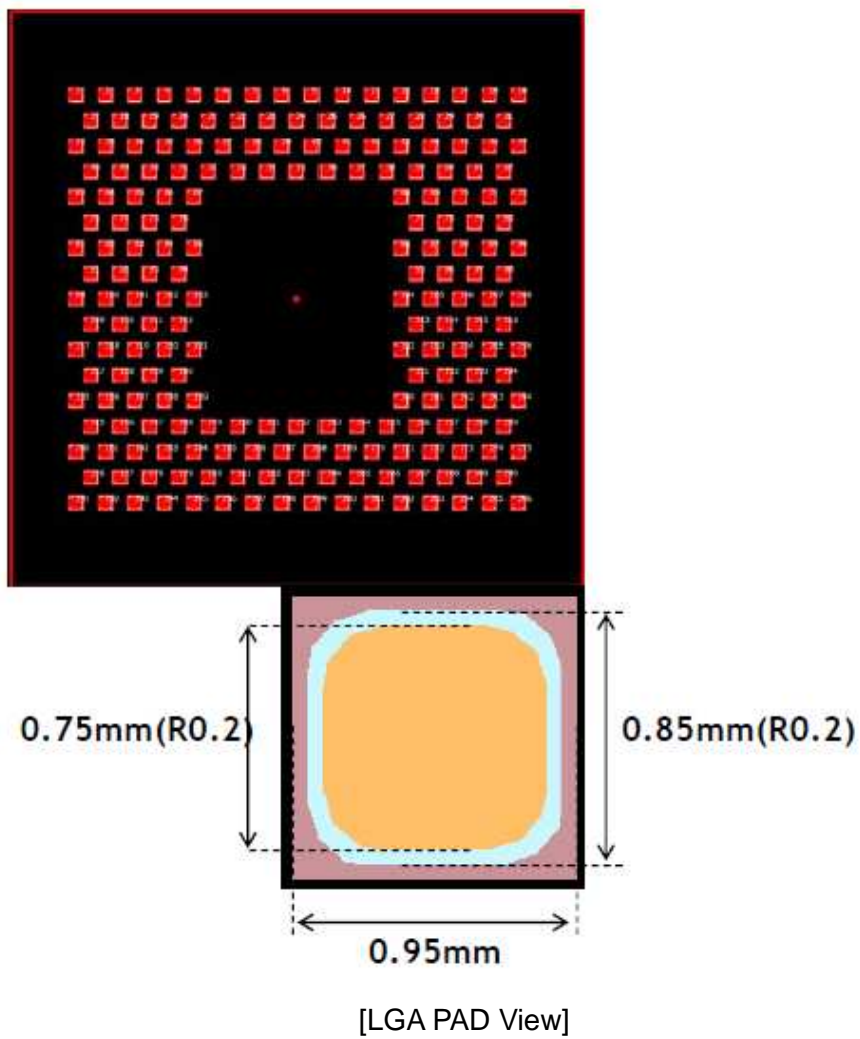
Table5. TM01LA-N Embedded Module Dimensions

Parameter	Nominal	Max	Units
Overall Dimension	35 x 35	35.35 x 35.35	mm
Overall Module Height	3.5	3.85	mm
PCB Thickness	1.0	1.1	mm
Flatness Specification		0.1	mm
Weight	tbd		g

1.4.2 Mechanical Drawing



1.4.3 Footprint



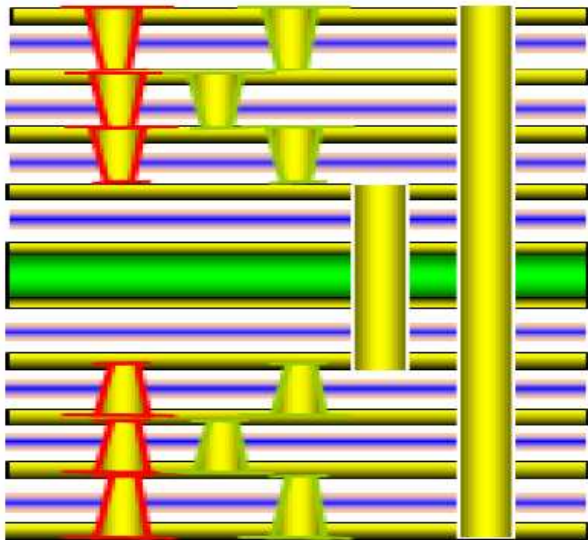
1.5 PCB information

1.5.1 PCB Stack up

Layer	Material		DK
	PSR	0.025	
1	Copper	0.035	
	Pre-Preg	0.060	3.98
2	Copper	0.025	
	Pre-Preg	0.060	3.98
3	Copper	0.025	
	Pre-Preg	0.060	3.98
4	Copper	0.025	
	Pre-Preg	0.110	4.15
5	Copper	0.015	

	Core	0.100	4.41
6	Copper	0.015	
	Pre-Preg	0.110	4.15
7	Copper	0.025	
	Pre-Preg	0.060	3.98
8	Copper	0.025	
	Pre-Preg	0.060	3.98
9	Copper	0.025	
	Pre-Preg	0.060	3.98
10	Copper	0.035	
	PSR	0.025	
		0.980	

1.5.2 PCB via structure



2. Pin Definitions

Pin No.	Name	Direction	Description
RF Antenna Pads			
12	ANT_MAIN	Input/Output	
15	ANT_DIVERSITY	Input	
GNSS Antenna Pad			
126	ANT_GNSS	Input	
Power Supply Pads			
81,82,91,92	+3.7V_VPWR	Input	Power Supply Input
114	VREG_MDME	Output	Voltage Reference Output (1.8V)
84	VDD_AUDIO_3.3V	Input	Audio codec power supply (typ 3.3V)
135	VCOIN_3.3V	Input	Coin Battery Input
USB Pads			

185	USB_VBUS	Input	USB Power Supply
198	USB_D+	Input/Output	Differential data interface positive
183	USB_D-	Input/Output	Differential data interface negative
199	USB_ID	Input	USB ID
UART Pads			
153	UART_RXD	Output	Receive Data (UART1)
169	UART_TXD	Input	Transmit Data (UART1)
154	UART2_RXD	Output	UART2 Receive Data
170	UART2_TXD	Input	UART2 Transmit Data
UIM Pads			
146	VREG_USIM	Output	Supply output for an UIM card
177	UIM_DET	Input	Detection of an external UIM card
162	UIM_RESET	Output	Reset output to an external UIM card
161	UIM_DATA	Input/Output	Data connection with an external UIM card
163	UIM_CLK	Output	Clock output to an external UIM card
GPIO I/F Pads			
172	GPIO1	Pull-Down	Available-GPIO
128	GPIO2	Pull-Down	Available-GPIO
150	GPIO3	Pull-Down	Available-GPIO
164	GPIO4	Pull-Down	Available-GPIO
139	GPIO5	Pull-Down	Available-GPIO
189	GPIO6	Pull-Down	Available-GPIO
137	GPIO7	Pull-Down	Available-GPIO
138	GPIO8	Pull-Down	Available-GPIO
148	GPIO9	Pull-Down	Available-GPIO
130	GPIO10	Pull-Down	Available-GPIO
Analog Audio I/F Pads			
2	AUDIO_INP1	Input	Microphone 1 input positive
3	AUDIO_INN1	Input	Microphone 1 input negative
17	AUDIO_INP2	Input	Microphone 2 input positive
18	AUDIO_INN2	Input	Microphone 2 input negative
19	AUDIO_LINE_IN	Input	Audio LINE_IN input
48	SPK_OUT3	Output	Speaker 3 output
64	SPK_OUT1	Output	Speaker 1 output
73	SPK_OUT2	Output	Speaker 2 output
HSIC I/F Pads			
195	HSIC_STB	Input/Output	HSIC Strobe signal
194	HSIC_DATA	Input/Output	HSIC data signal
196	HSIC_CAL	Input/Output	HSIC calibration pad
Reset Pads			
147	RESET_N	Input	External H/W Reset Input
133	RESOUT_N	Output	MDM Reset Output
ADC I/F Pads			

129	ADC2	Input	Analog to Digital Converter Input
204	ADC1	Input	Analog to Digital Converter Input
LED I/F Pad			
188	LED	Output	LED Driver control
SPI I/F Pads			
171	SPI_CLK	Output	SPI Serial Clock
186	SPI_MISO	Input	SPI Serial input
201	SPI_MOSI	Output	SPI Serial output
202	SPI_CS_N	Output	SPI Chip Select
ON/OFF Pad			
173	ON/OFF	Input	ON/OFF Control
SDIO I/F Pads			
140	SDIO_DATA0	Input/Output	SDIO Data bit 0
122	SDIO_DATA1	Input/Output	SDIO Data bit 1
141	SDIO_DATA2	Input/Output	SDIO Data bit 2
142	SDIO_DATA3	Input/Output	SDIO Data bit 3
131	SDIO_CMD	Output	SDIO Command
132	SDIO_CLK	Output	SDIO Clock
I2C I/F Pads			
117	I2C_SCL	Output	I2C Clock output
109	I2C_SDA	Input/Output	I2C Data
JTAG I/F Pads			
159	TRST/	Input	Debugging
124	TDI	Input	Debugging
190	TMS	Input	Debugging
175	TCK	Input	Debugging
143	RTCK	Output	Debugging
174	TDO	Output	Debugging
206	JTAG_PS_HOLD	Input	Debugging
166	JTAG_RESIN_NN	Input	Debugging
113	VREG_MDME	Output	Power Supply JTAG (1.8V)
Reserved			
203	ADC5		Reserved (PMIC MPP_05)
74	AUDIO_RST/		Reserved
75	DEBUG_AUDIO_RST/		Reserved
93	DEBUG_SDOUT3		Reserved
94	I2S_DOUT		Reserved
99	DEBUG_I2C_SCL		Reserved
100	DEBUG_I2C_SDA		Reserved
101	DEBUG_SDOUT2		Reserved
102	I2S_CLK		Reserved
103	I2S_WS		Reserved
110	I2S_DIN		Reserved
111	WIFI_PM_EN		Reserved
112	WIFI_CLK_REQ		Reserved

120	WIFI_RESET_N		Reserved
180	GPIO68		Reserved
181	GPIO65		Reserved
182	GPIO66		Reserved
197	GPIO67		Reserved
158	PBL_STATUS/HSIC_RST_N		Reserved
145	XO_OUT	Clock	Reserved
155	UART_RTS/		Reserved
156	UART_CTS/		Reserved
160	TCU_PCM_RXD		Reserved
165	WAKE_N		Reserved
176	TCU_PCM_CLK		Reserved
191	TCU_PCM_FRAME		Reserved
192	TCU_PCM_TXD		Reserved
200	I2S_MCLK		Reserved
205	NDR_PULSE		Reserved
149	GPIO_49		Reserved
Ground			
1,4,5,6,7,8,9,10,11,13, 14,16,20,21,22,23,24, 25,26,27,28,29,30,31, 32,33,34,35,36,37,38,39 ,40,41,42,43,44,45,46,4 7,49,50,51,52,53,54,55, 56,57,58, 59,60,61,62,63, 65,66,67,68,69, 70,71,72,76,77, 78,79,80,83,85, 86,87,88,89,90, 95,96,97,98,104, 105,106,107,108,115, 116,118,119,121,123, 125,127,134,136,144, 151,152,157,167,168, 178,179,184,187,193,20 7,208,209,210,211,212, 213,214,215,216,217,21 8	GND	Ground	GND

2.1 VCOIN

The TM01LA-N provides an interface for a coin cell to maintain the internal RTC when +3.7V_VPWR is removed from the TM01LA-N device. Whenever +3.7V_VPWR is applied the RTC is powered from the +3.7V_VPWR supply.

Table7. VCOIN Interface Specification

VCOIN	Min	Typ	Max	Units
DC Power Input Range	2	3	3.2	V
Current Draw		1.1	2.0	μA

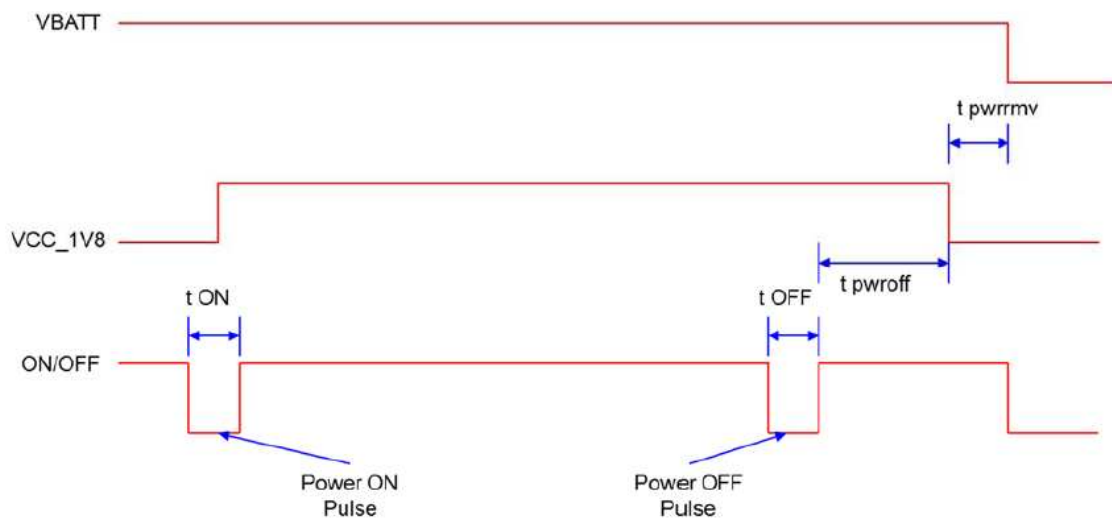
2.2 ON/OFF Control

The ON/OFF signal is internally pulled up to an internal 1.8V reference voltage. An open drain transistor should be connected to this pin to generate a low pulse. This pin should not be driven high external to the TM01LA-N embedded module.

2.2.1 ON/OFF Timing (TBD)

The ON/OFF pin is a low pulse toggle control. The first pulse powers the TM01LA-N ON, a second pulse instructs the TM01LA-N to begin the Shutdown process.

The diagram below illustrates the recommended application implementation for ON/OFF control.



The diagram below illustrates an alternate application implementation that holds ON/OFF low during operation.

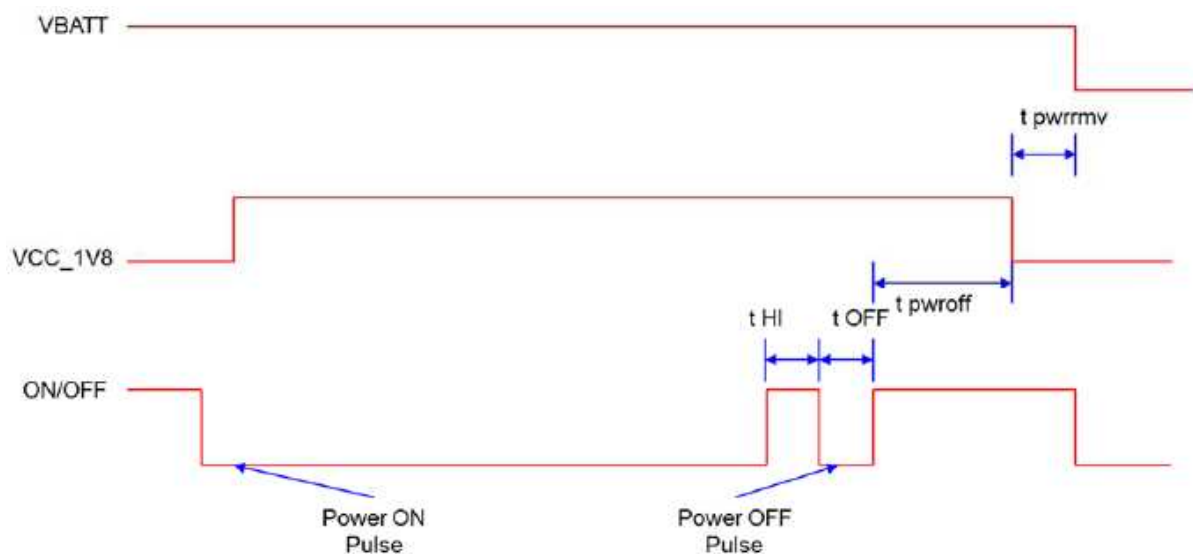


Table8. Power-ON Sequence Symbol Definitions (TBD)

Symbol	Parameter	Min	Typ	Max
t ON	Turn ON Pulse duration	TBD	TBD	
t OFF	Turn OFF Pulse duration	TBD	TBD	TBD
t pwoff	Time to Power OFF	-	TBD	
t pwrmv	Time +3.7V_VPWR must be maintained after VREG_MDME goes inactive	TBD		
t HI	Time required for ON/OFF to be high prior to OFF pulse.	TBD		
		TBD		

T pwoff is the time between when a power OFF pulse is complete and when shutdown is completed by the TM01LA-N devices. This duration is network and device dependent, i.e. in a CDMA network a power down registration is initiated by the TM01LA-N device, when the acknowledgement is received from the network power OFF completes.

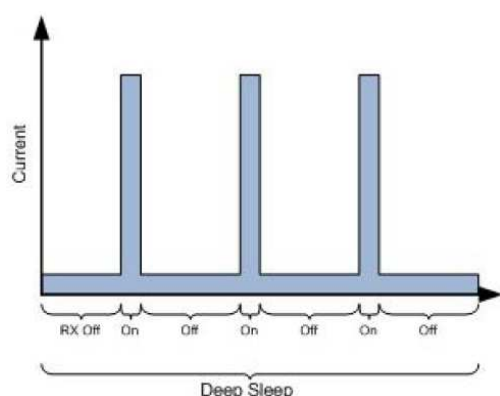
Detection of power down can be accomplished by monitoring for one of the following:

- +WIND: 10 output on the AT Command interface
- USB ports are de-enumerated

The application must wait for a power down to be detected prior to removing power from the TM01LA-N device. If a timeout is required, it is recommended to be in excess of 30s prior to removing power from the TM01LA-N device.

2.2.2 Deep Sleep

The TM01LA-N embedded modules support a low power mode in which the device is registered on the LTE/GSM/WCDMA network and sleeps in between wake intervals where it listens for pages.



The following table lists the parameter that defines the wake interval period for the various devices.

Table9. Period of Wake Intervals

Device	Network Standard	Parameter
TM01LA-N	GSM	DRX
	WCDMA	DRX
	LTE	DRX

The DRX cycle index values are broadcast by the wireless network on which the TM01LA-N embedded module is registered.

While in Deep Sleep mode the functions of the TM01LA-N are limited as defined in the following table.

Table10. Deep Sleep Function Availability

Function	Availability	Conditions
Paging	√	
GNSS		GNSS is powered down
Time measurement	√	
USB		USB_VBUS is not applied
UART		
Digital IO		Digital IO pins maintained last state

Events that cause the TM01LA-N to wake-up from Deep Sleep mode include:

- Incoming call
- Expiration of an internal timer in the TM01LA-N
- USB_VBUS is applied to the TM01LA-N
- WAKE_N is asserted (low)
- UART1 DTR is asserted (high) if UART1 DTR has been enabled as a sleep control (AT+W32K=1,1) and AT Command Service is mapped to UART1
- GNSS location fix request is initiated from an Embedded Application

2.2.3 Sequence to Enter Deep Sleep Mode

The following list defines the sequence needed by the application to allow the TM01LA-N to enter Deep Sleep mode:

1. TM01LA-N has registered on the WWAN network (or callbox), and is not in a call.
2. End GNSS Tracking session.
3. Turn off GNSS Antenna bias.
4. Confirm WAKE_N is not held low (pulled-up in TML1-X).
5. Ensure UARTs are in the inactive state.
6. Remove VBUS from being applied to the AR device.
7. Ensure UARTs are in the inactive state.
8. Remove VBUS from being applied to the AR device.

2.3 USB

The TM01LA-N has a High Speed USB2.0 compliant, peripheral only interface. The TM01LA-N don't support OTG.

The TM01LA-N will not be damaged if a valid USB_VBUS is supplied while the main DC power is not supplied.

Table10. USB Characteristics

USB		Value	Units
USB_VBUS	Voltage range	2.0 – 5.25	V
	Maximum Current draw ¹	1	mA
	Maximum Input Capacitance (Min ESR = 50 mΩ)	10	μF

¹With the TM01LA-N device powered ON.

2.4 UART

The TM01LA-N has two UART interfaces. The primary UART is an 4-wire electrical interface and the secondary UART is a 2-wire electrical interface.

Table11. UART Interface PADS

Pin No.	Name	Direction	Description
153	UART_RXD	Output	Receive Data (UART1)
169	UART_TXD	Input	Transmit Data (UART1)
154	UART2_RXD	Output	Receive Data (UART2)
170	UART2_TXD	Input	Transmit Data (UART2)
155	UART_RTS/	Output	Request To Send(UART1)
156	UART_CTS/	Input	Clear To Send(UART1)

2.5 UIM Interface

The UIM interface of the TM01LA-N supports a USIM for LTE, WCDMA and GSM.

Table13. UIM Interface PADS

Pin No.	Name	Direction	Description
146	VREG_USIM	Output	Supply output for an UIM card
177	UIM_DET	Input	Detection of an external UIM card
162	UIM_RESET	Output	Reset output to an external UIM card
161	UIM_DATA	Input/Output	Data connection with an external UIM card
163	UIM_CLK	Output	Clock output to an external UIM card

2.6 General Purpose IO

The TM01LA-N defines 10 GPIOs for customer use.

Table14. GPIO Interface PADs

Pin No.	Name	Direction	Description
172	GPIO1	Pull-Down	Available-GPIO
128	GPIO2	Pull-Down	Available-GPIO
150	GPIO3	Pull-Down	Available-GPIO
164	GPIO4	Pull-Down	Available-GPIO
139	GPIO5	Pull-Down	Available-GPIO
189	GPIO6	Pull-Down	Available-GPIO
137	GPIO7	Pull-Down	Available-GPIO
138	GPIO8	Pull-Down	Available-GPIO
148	GPIO9	Pull-Down	Available-GPIO
130	GPIO10	Pull-Down	Available-GPIO

2.7 Secure Digital IO

The TM01LA-N defines a 1.8V SDIO interface for future use.

Table15. SDIO Interface PADs

Pin No.	Name	Direction	Description
140	SDIO_DATA0	Input/Output	SDIO Data bit 0
122	SDIO_DATA1	Input/Output	SDIO Data bit 1
141	SDIO_DATA2	Input/Output	SDIO Data bit 2
142	SDIO_DATA3	Input/Output	SDIO Data bit 3
131	SDIO_CMD	Output	SDIO Command
132	SDIO_CLK	Output	SDIO Clock

2.8 I2C Interface

The TM01LA-N provides an I2C interface.

The I2C signals are open drain outputs with 2.2 k Ω pull-up resistors to VREG_MDME (1.8V) internal to the TML1-X.

Table16. I2C Interface PADs

Pin No.	Name	Direction	Description
117	I2C_SCL	Output	I2C Clock output
109	I2C_SDA	Input/Output	I2C Data

2.9 RESET

The TM01LA-N provides an interface to allow an external application to RESET the module as well as an output to indicate the current RESET state or control an external device.

The RESIN_N signal is pulled-up internal to the TML1-X. An open collector transistor or equivalent should be used to Ground the signal when necessary to RESET the module.

Note: Use of the RESIN_N signal to RESET the TM01LA-N could result in memory corruption if used inappropriately. This signal should only be used if the TM01LA-N has become unresponsive and it is not possible to perform a power cycle.

Table17. Reset Timing

Symbol	Parameter	Min	Typ	Max
Trdet	Duration of RESIN_N signal before firmware detects it (debounce timer)		tbd	
Trlen	Duration reset asserted	tbd		
Trdel	Delay between minimum Reset duration and Internal Reset generated		tbd	

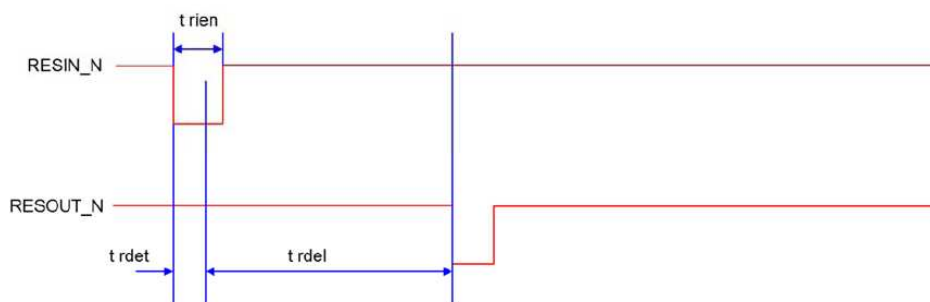


Figure . Illustration of Reset Timing When RESIN_N < Trdel

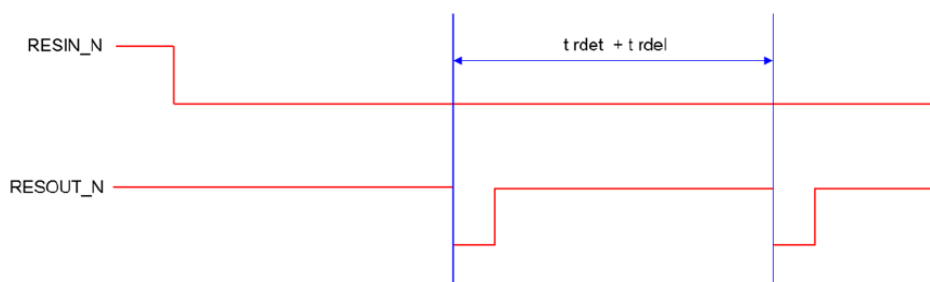


Figure. Illustration of Reset Timing When RESIN_N Held Low > Trdet+Trdel

2.10 ADC

The TM01LA-N provides two ADC inputs. The interface information is provided in the tables below.

Table18. ADC Interface Characteristics

ADC		Value	Units
ADCx	Full-Scale Voltage Level	0.05 ~ 1.75	V
	Resolution	15	bit
	Sample rate	1.15(tbd)	KHz
	Input Impedance	>4	MΩ

2.11 LED driver

The TM01LA-N provides an LED driver. The LED driver is a programmable current sink.

Table19. LED Interface PAD

Pin No.	Name	Direction	Description
188	LED	Output	LED Driver control

2.12 Audio

The TM01LA-N supports Analog audio interfaces.

The ADC blocks supports Stereo 24-bit Inputs (Differential, Single-ended) and Mono 24-bit (Line-In).

The DAC blocks supports Stereo 24-bit output (Stereo) and Line output (Single-ended).

Table20. Audio Interface PADs

Pin No.	Name	Direction	Description
2	AUDIO_INP1	Input	Microphone 1 input positive
3	AUDIO_INN1	Input	Microphone 1 input negative
17	AUDIO_INP2	Input	Microphone 2 input positive
18	AUDIO_INN2	Input	Microphone 2 input negative
19	AUDIO_LINE_IN	Input	Audio LINE_IN input
48	SPK_OUT3	Output	Speaker 3 output
64	SPK_OUT1	Output	Speaker 1 output
73	SPK_OUT2	Output	Speaker 2 output

2.13 SPI Interface

The TM01LA-N embedded module provides one SPI bus (4-wire interface).

SPI bus interface includes:

- A CLK signal
- An O signal
- An I signal
- A CS (Chip Select) signal

The following features are available on the SPI bus :

- Master-only mode operation
- SPI speed is from 128 kbit/s to 26Mbit/s in master mode operation
- 4-wire interface
- 4 to 32 bits data length.

Table21. SPI Interface PADS

Pin No.	Name	Direction	Description
171	SPI_CLK	Output	SPI Serial Clock
186	SPI_MISO	Input	SPI Serial input
201	SPI_MOSI	Output	SPI Serial output
202	SPI_CS_N	Output	SPI Chip Select

2.14 HSIC Interface

The TM01LA-N embedded module provides one HSIC bus (2-wire interface).

HSIC bus interface includes:

- HSIC strobe signal
- HSIC data signal
- Calibration pad for HSIC port signal

Table22. HSIC Interface PADS

Pin No.	Name	Direction	Description
195	HSIC_STB	Input/Output	HSIC Strobe signal
194	HSIC_DATA	Input/Output	HSIC data signal
196	HSIC_CAL	Input/Output	HSIC calibration pad

2.15 JTAG Interface

JTAG test points on customer application are recommended for possible failure analysis if necessary in the future.

Table23. JTAG Interface PADS

Pin No.	Name	Direction	Description
159	TRST/	Input	Debugging

124	TDI	Input	Debugging
190	TMS	Input	Debugging
175	TCK	Input	Debugging
143	RTCK	Output	Debugging
174	TDO	Output	Debugging
206	JTAG_PS_HOLD	Input	Debugging
166	JTAG_RESIN_NN	Input	Debugging
113	VREG_MDME	Output	Power Supply JTAG (1.8V)

3. RF Specification

The specifications for the LTE, GSM and WCDMA interfaces are defined.

TM01LA-N is designed to be compliant with the standard shown in the table below.

Table24. Standards Compliance

Technology	Standards
UMTS (WCDMA)	• 3GPP Release 5
	• 3GPP Release 6
	• 3GPP Release 7
	• 3GPP Release 8
LTE	• 3GPP Release 8
GSM/GPRS/EDGE	• 3GPP Release R99

3.1 WCDMA B1, B2, B4, B5 Specification

3.1.1 WCDMA TX Output Power

The Maximum / Minimum Transmitter Output Power of the TM01LA-N are specified in the following table.

Table25.

Band	Method (UL CH)	Specification
WCDMA Band 2 Power Level	Measure Max and Min Transmit Power of Low Channel (CH=9263) in WCDMA B2 Mode	Max Power : 20.2~24.2dBm Min Power : ≤ -50dBm
	Measure Max and Min Transmit Power of Middle Channel (CH=9400) in WCDMA B2 Mode	Max Power : 20.2~24.2dBm Min Power : ≤ -50dBm
	Measure Max and Min Transmit Power of High Channel (CH=9537) in WCDMA B2 Mode	Max Power : 20.2~24.2dBm Min Power : ≤ -50dBm
WCDMA Band 4 Power Level	Measure Max and Min Transmit Power of Low Channel (CH=1313) in WCDMA B4 Mode	Max Power : 20.2~24.2dBm Min Power : ≤ -50dBm
	Measure Max and Min Transmit Power of Middle Channel (CH=1413) in WCDMA B4 Mode	Max Power : 20.2~24.2dBm Min Power : ≤ -50dBm
	Measure Max and Min Transmit Power of High Channel (CH=1513) in WCDMA B4 Mode	Max Power : 20.2~24.2dBm Min Power : ≤ -50dBm
WCDMA Band 5 Power Level	Measure Max and Min Transmit Power of Low Channel (CH=4133) in WCDMA B5 Mode	Max Power : 20.2~24.2dBm Min Power : ≤ -50dBm
	Measure Max and Min Transmit Power of Middle Channel (CH=4183) in WCDMA B5 Mode	Max Power : 20.2~24.2dBm Min Power : ≤ -50dBm
	Measure Max and Min Transmit Power of High Channel (CH=4232) in WCDMA B5 Mode	Max Power : 20.2~24.2dBm Min Power : ≤ -50dBm

3.1.2 WCDMA RX Sensitivity

The Receiver Sensitivity of the TM01LA-N are specified in the following table.

Table26. Conducted RX (Receive) Sensitivity – WCDMA Bands

Item	Method (DL CH)	Specification
WCDMA Band 2 BER(Bit Error Rate)	Measure BER of Low Channel (CH=9663) in WCDMA B2 Mode	0~0.1% @ <-104.7dBm
	Measure BER of Middle Channel (CH=9800) in WCDMA B2 Mode	0~0.1% @ <-104.7dBm
	Measure BER of High Channel (CH=9937) in WCDMA B2 Mode	0~0.1% @ <-104.7dBm
WCDMA Band 4 BER(Bit Error Rate)	Measure BER of Low Channel (CH=1538) in WCDMA B4 Mode	0~0.1% @ <-106.7dBm
	Measure BER of Middle Channel (CH=1675) in WCDMA B4 Mode	0~0.1% @ <-106.7dBm
	Measure BER of High Channel (CH=1737) in WCDMA B4 Mode	0~0.1% @ <-106.7dBm
WCDMA Band 5 BER(Bit Error Rate)	Measure BER of Low Channel (CH=4358) in WCDMA B5 Mode	0~0.1% @ <-104.7dBm
	Measure BER of Middle Channel (CH=4400) in WCDMA B5 Mode	0~0.1% @ <-104.7dBm
	Measure BER of High Channel (CH=4457) in WCDMA B5 Mode	0~0.1% @ <-104.7dBm

3.2. LTE B2, B4, B5, B7, B17 Specification

3.2.1 LTE TX Output Power

The Maximum / Minimum Transmitter Output Power of the TM01LA-N are specified in the following table.

Table27. Conducted TX (Transmit) Max output Power Tolerances – LTE Bands

BAND	Method (UL CH)	Specification
BAND2 UE Maximum Output Power	Measure Max and Min Transmit Power of Low Channel (650)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
	Measure Max and Min Transmit Power of Mid Channel (900)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
	Measure Max and Min Transmit Power of High Channel (1150)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
BAND4 UE Maximum Output Power	Measure Max and Min Transmit Power of Low Channel (2000)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
	Measure Max and Min Transmit Power of Mid Channel (2175)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
	Measure Max and Min Transmit Power of High Channel (2350)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
BAND5 UE Maximum Output Power	Measure Max and Min Transmit Power of Low Channel (2450)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
	Measure Max and Min Transmit Power of Mid Channel (2525)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
	Measure Max and Min Transmit Power of High Channel (2600)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
BAND7 UE Maximum Output Power	Measure Max and Min Transmit Power of Low Channel (2800)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
	Measure Max and Min Transmit Power of Mid Channel (3100)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
	Measure Max and Min Transmit Power of High Channel (3400)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
BAND17 UE Maximum Output Power	Measure Max and Min Transmit Power of Low Channel (23735)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
	Measure Max and Min Transmit Power of Mid Channel (23790)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm
	Measure Max and Min Transmit Power of High Channel (23845)	Max Power : 19.3~25.7dBm Min Power : ≤ -39dBm

3.2.2 LTE RX Sensitivity

The Receiver Sensitivity of the TM01LA-N are specified in the following table.

Table28. Conducted RX (Receive) Sensitivity – LTE Bands

BAND	Method (DL CH)	Specification
BAND2 Reference sensitivity level(DUAL)	Measure BLER of Low Channel (650) in Band2	sensitivity : ≤-95 BLER : ≤ 5%
	Measure BLER of Mid Channel (900) in Band2	sensitivity : ≤-95 BLER : ≤ 5%
	Measure BLER of High Channel (1150) in Band2	sensitivity : ≤-95 BLER : ≤ 5%
BAND 4 Reference	Measure BLER of Low Channel (2000) in Band4	sensitivity : ≤-97 BLER : ≤ 5%

sensitivity level(DUAL)	Measure BLER of Mid Channel (2175) in Band4	sensitivity : ≤ -97 BLER : $\leq 5\%$
	Measure BLER of High Channel (2350) in Band4	sensitivity : ≤ -97 BLER : $\leq 5\%$
BAND 5 Reference sensitivity level(DUAL)	Measure BLER of Low Channel (2450) in Band5	sensitivity : ≤ -95 BLER : $\leq 5\%$
	Measure BLER of Mid Channel (2525) in Band5	sensitivity : ≤ -95 BLER : $\leq 5\%$
	Measure BLER of High Channel (2600) in Band5	sensitivity : ≤ -95 BLER : $\leq 5\%$
BAND 7 Reference sensitivity level(DUAL)	Measure BLER of Low Channel (2800) in Band7	sensitivity : ≤ -95 BLER : $\leq 5\%$
	Measure BLER of Mid Channel (3100) in Band7	sensitivity : ≤ -95 BLER : $\leq 5\%$
	Measure BLER of High Channel (3400) in Band7	sensitivity : ≤ -95 BLER : $\leq 5\%$
BAND 17 Reference sensitivity level(DUAL)	Measure BLER of Low Channel (5735) in Band12	sensitivity : ≤ -94 BLER : $\leq 5\%$
	Measure BLER of Mid Channel (5790) in Band12	sensitivity : ≤ -94 BLER : $\leq 5\%$
	Measure BLER of High Channel (5845) in Band12	sensitivity : ≤ -94 BLER : $\leq 5\%$

3.3 GSM 850, 900,1800, 1900 Specification

3.3.1 GSM TX Output Power

The Maximum Transmitter Output Power of the TM01LA-N are specified in the following table.

Table29. Conducted TX (Transmit) Max output Power Tolerances – GSM/EDGE Bands

Item	Method (DL CH)	Specification
GSM850 Power Level	Measure Max Transmit Power of Low Channel (CH=128) in GSM850 Mode	Max Power : 31.0~33.5dBm
	Measure Max Transmit Power of Middle Channel (CH=189) in GSM850 Mode	Max Power : 31.0~33.5dBm
	Measure Max Transmit Power of High Channel (CH=251) in GSM850 Mode	Max Power : 31.0~33.5dBm
EGSM900 Power Level	Measure Max Transmit Power of Low Channel (CH=975) in EGSM Mode	Max Power : 31.0~33.5dBm
	Measure Max Transmit Power of Middle Channel (CH=38) in EGSM Mode	Max Power : 31.0~33.5dBm
	Measure Max Transmit Power of High Channel (CH=124) in EGSM Mode	Max Power : 31.0~33.5dBm
DCS1800 Power Level	Measure Max Transmit Power of Low Channel (CH=512) in DCS1800 Mode	Max Power : 28.0~30.5dBm
	Measure Max Transmit Power of Middle Channel (CH=660) in DCS1800 Mode	Max Power : 28.0~30.5dBm
	Measure Max Transmit Power of High Channel (CH=885) in DCS1800 Mode	Max Power : 28.0~30.5dBm
PCS1900 Power Level	Measure Max Transmit Power of Low Channel (CH=512) in DCS1900 Mode	Max Power : 28.0~30.5dBm
	Measure Max Transmit Power of Middle Channel (CH=660) in DCS1900 Mode	Max Power : 28.0~30.5dBm
	Measure Max Transmit Power of High Channel (CH=810) in DCS1900 Mode	Max Power : 28.0~30.5dBm

3.3.2 GSM RX Sensitivity

The Receiver Sensitivity of the TM01LA-N are specified in the following table.

Table30. Conducted RX (Receive) Sensitivity – GSM/EDGE Bands

Item	Method (DL CH)	Specification
GSM850 BER(Bit Error Rate)	Measure BER of Low Channel (CH=128) in GSM850 Mode	0~2.439% @<-102dBm
	Measure BER of Middle Channel (CH=189) in GSM850 Mode	0~2.439% @<-102dBm
	Measure BER of High Channel (CH=251) in GSM850 Mode	0~2.439% @<-102dBm
EGSM900 BER(Bit Error Rate)	Measure BER of Low Channel (CH=975) in EGSM Mode	0~2.439% @<-102dBm
	Measure BER of Middle Channel (CH=38) in EGSM Mode	0~2.439% @<-102dBm
	Measure BER of High Channel (CH=124) in EGSM Mode	0~2.439% @<-102dBm
DCS1800 BER(Bit Error Rate)	Measure BER of Low Channel (CH=512) in DCS1800 Mode	0~2.439% @<-102dBm
	Measure BER of Middle Channel (CH=660) in DCS1800 Mode	0~2.439% @<-102dBm
	Measure BER of High Channel (CH=885) in DCS1800 Mode	0~2.439% @<-102dBm
PCS1900 BER(Bit Error Rate)	Measure BER of Low Channel (CH=512) in PCS1900 Mode	0~2.439% @<-102dBm
	Measure BER of Middle Channel (CH=660) in PCS1900 Mode	0~2.439% @<-102dBm
	Measure BER of High Channel (CH=810) in PCS1900 Mode	0~2.439% @<-102dBm

4. GNSS

The TM01LA-N includes optional Global Navigation Satellite System(GNSS) capabilities via the Qualcomm gpsOne Gen8A Engine, capable of operation in assisted and stand-alone GPS modes as well as GPS+GLONASS mode.

Table33. Position location and navigation summary(gpsOne™)

Standard	Feature descriptions
gpsOne with global navigation satellite system (GNSS) support	
Gen8A	■ Global positioning system (GPS)
	□ Next-generation gpsOne™ solution with enhanced GNSS engine and low power tracking
	□ Enhanced navigation 3.0, dynamic power optimization, and on-demand positioning
	□ Support for Wi-Fi positioning
	□ MS/UE-based, MS/UE-assisted, hybrid modes with AFLT (CDMA), NMR (GSM), and MRL(UMTS, WCDMA, LTE), standalone and network-aware modes
	□ gpsOneXTRA Assistance for enhanced standalone GNSS performance
	□ Control plane: IS-801, IS-881, and UMTS CP assisted-GNSS protocols

<ul style="list-style-type: none"> □ User plane: v1/v2 trusted mode and OMA SUPL 2.0 assisted-GPS protocols □ Wideband processing of GPS signals helps resolve multipath interference, promoting improved measurement accuracy ■ Support for GLONASS standalone mode □ GLONASS capability increases the number of satellites available to the positioning engine, resulting in an expanded area of coverage over traditional GPS receivers
--

4.1 GNSS Characteristics

The GNSS implementation supports GPS L1 operation and GLONASS L1 FDMA operation.

Table34. GNSS Characteristics

Parameter		Value
*Sensitivity	Standalone or MS Based Tracking Sensitivity	TBD
	Cold Start Sensitivity	TBD
	MS Assisted Synchronous A-GNSS Acquisition Sensitivity	TBD
Accuracy in Open Sky (1 Hz tracking)		<2m CEP-50
Total number of SV available		~30 SVs
Support for Predicted Orbits		Yes
Predicted Orbit CEP-50 Accuracy		5 m
Standalone Time To First Fix (TTFF)	Super Hot	1 s
	Warm	29 s
	Cold	32 s
GNSS Message Protocols		NMEA

Note: Acquisition/Tracking Sensitivity performance figures assume open sky w/ active patch GNSS antenna and a 2.5 dB Noise Figure.

4.2 GNSS Antenna Interface

Table35. GNSS Antenna Interface Characteristics

Characteristics		GNSS
Frequency	GPS L1 (Wideband)	1575.42 ± 20 MHz
	Glonass L1 FDMA	1597.5 – 1605.8 MHz
RF Impedance		50 Ω
VSWR max	RX	2:1

4.3 Active antenna Powering the External LNA

The external LNA needs a source of power. Many of the active antennas accept a 3 volt or 5 volt DC voltage that is impressed upon the RF signal line. This voltage is not supplied by the TML1-X, but can be easily supplied by the host design.

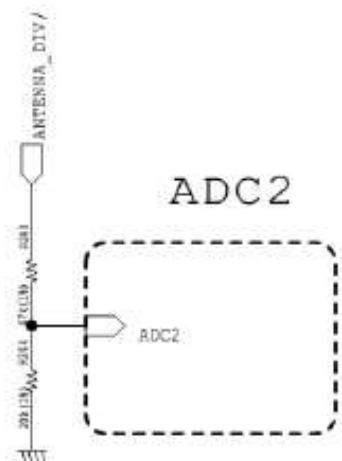
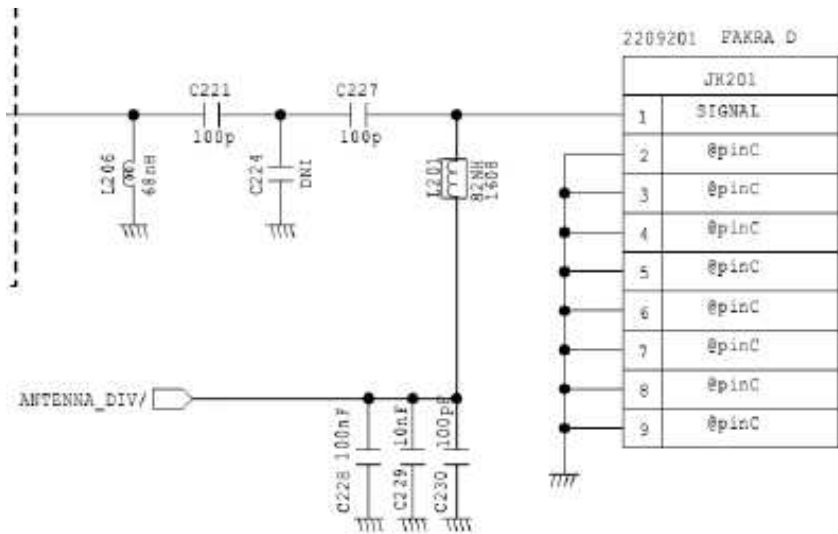
4.3.1 External LNA Enable

The electrical characteristics of the GNSS_LNA_EN signal are:

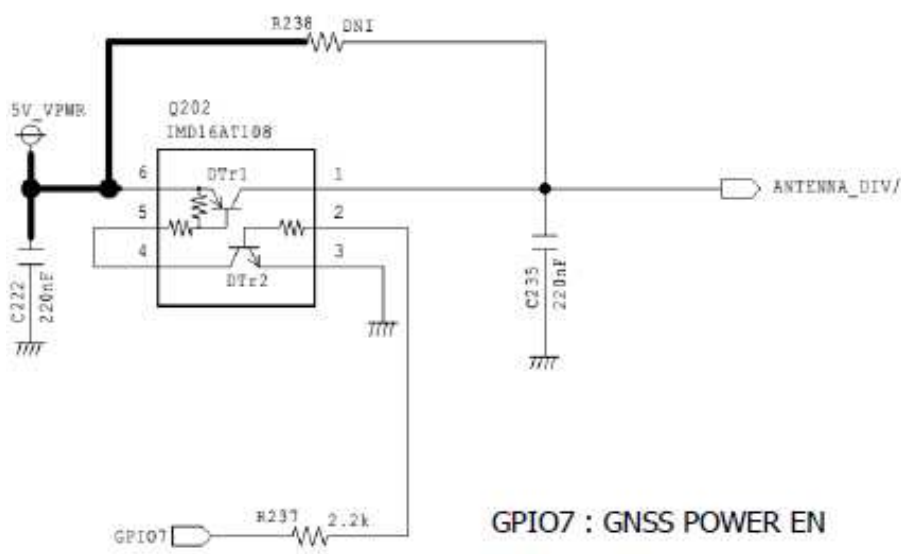
Table36. GNSS_LNA EN Table

Parameter		Min	Typ	Max	Units
GNSS_LNA_EN	Output high level	1.6		1.9	V
	Output low level	0		0.2	V

An example of GPS Antenna Supply circuit is shown in the following image:



[460]GNSS Antenna supply



<FCC Warning Statements>

FCC Part 15.19 Statements:

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

FCC Part 15.21 statement

Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

RF Exposure Statement

The antenna(s) must be installed such that a minimum separation distance of at least 20 cm is maintained between the radiator (antenna) and all persons at all times. This device must not be co-located or operating in conjunction with any other antenna or transmitter.

The highest permitted antenna gains including cable loss for use with this device are: GSM850 / WCDMA850 : -3.25 dBi, GSM1900 / WCDMA1900 : 1.26 dBi, WCDMA1700 : -0.13 dBi, LTE Band 2: 1.26 dBi, LTE Band 5: -3.25 dBi, LTE Band 17: -3.03 dBi, LTE Band 4: -0.13 dBi, LTE Band 7: -0.22 dBi, LTE Band 12: -3.03 dBi..

End Product Labeling

The module is labeled with its own FCC ID. If the FCC ID is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. In that case, the final end product must be labeled in a visible area with the following:

"Contains FCC ID: BEJLGAJ10N

" Contains IC: 2703H-LGAJ10N

OEM Responsibilities to comply with FCC Regulations

The module has been certified for integration into products only by OEM integrators under the following condition:

- The antenna(s) must be installed such that a minimum separation distance of at least 20 cm is maintained between the radiator (antenna) and all persons at all times.
- The transmitter module must not be co-located or operating in conjunction with any other antenna or transmitter except in accordance with FCC multi-transmitter product procedures.

As long as the two condition above is met, further transmitter testing will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed (for example, digital device emissions, PC peripheral requirements, etc.).

IMPORTANT NOTE: In the event that these conditions can't be met (for certain configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID can't be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

Manual Information To the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module or change RF related parameters in the user manual of the end product.

L'exposition aux RF

L'antenne (ou les antennes) doit être installée de façon à maintenir à tout instant une distance minimum de au moins 20 cm entre la source de radiation (l'antenne) et toute personne physique.

Étiquetage du produit final

Le module BT111 est étiqueté avec sa propre identification FCC et son propre numéro de certification IC. Si l'identification FCC et le numéro de certification IC ne sont pas visibles lorsque le module est installé à l'intérieur d'un autre dispositif, la partie externe du dispositif dans lequel le module est installé devra également présenter une étiquette faisant référence au module inclus. Dans ce cas, le produit final devra être étiqueté sur une zone visible avec les informations suivantes :

« Contient module émetteur identification FCC ID : BEJLGAJ10N

« Contient module émetteur IC : 2703H-LGAJ10N

RSS-GEN, Sec. 8.3

This radio transmitter (identify the device by certification number, or model number if Category II) has been approved by Industry Canada to operate with the antenna types listed below with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Le présent émetteur radio (identifier le dispositif par son numéro de certification ou son numéro de modèle s'il fait partie du matériel de catégorie I) a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés ci-dessous et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.